



Product Change Notification

Change Notification #: 117238 - 00

Change Title: Intel® Omni-Path Director Class Switch 100 Series 24 Slot Base 1MM 100SWD24B1N,
Intel® Omni-Path Director Class Switch 100 Series 6 Slot Base 1MM 100SWD06B1N,
Intel® Omni-Path Director Switch Leaf Module 100 Series 32 port 100SWDLF32Q,
Intel® Omni-Path Director Switch Leaf Module 100 Series 48 port 100SWDLF48D,
Intel® Omni-Path Director Switch Management Module 100 Series 100SWDMGTSH

PCN 117238 - 00, Product Design, Label, Firmware and FPGA Updates, Regulatory Label Addition

Date of Publication: October 31, 2019

Key Characteristics of the Change:

Product Design, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	December 1, 2019
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The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Affected Product Code	Product Description
100SWD06B1N	Intel® Omni-Path Director Class Switch 100 Series 6 Slot Base 1MM 100SWD06B1N
100SWD24B1N	Intel® Omni-Path Director Class Switch 100 Series 24 Slot Base 1MM 100SWD24B1N
100SWDMGTSH	Intel® Omni-Path Director Switch Management Module 100 Series 100SWDMGTSH
100SWDLF32Q	Intel® Omni-Path Director Switch Leaf Module 100 Series 32 port 100SWDLF32Q
100SWDLF48D	Intel® Omni-Path Director Switch Leaf Module 100 Series 48 port 100SWDLF48D

Overview of Changes:

Change 1: A regulatory label will be added to all leaf modules.

Change 2: The switch firmware version shall be updated from 10.5.1 to 10.8.0.

Change 3: The FPGA image on switch management and leaf modules shall be updated.

Product Change Details:

Change 1: In order to facilitate shipment of leaf modules into Korea and Taiwan, a dedicated Registration of Compatibility and associated label, independent of the Director Class chassis, will be added. These regulatory labels are shown in **Figure 1** and **Figure 2** below.

Figure 1. 100SWDLF32Q Regulatory Label

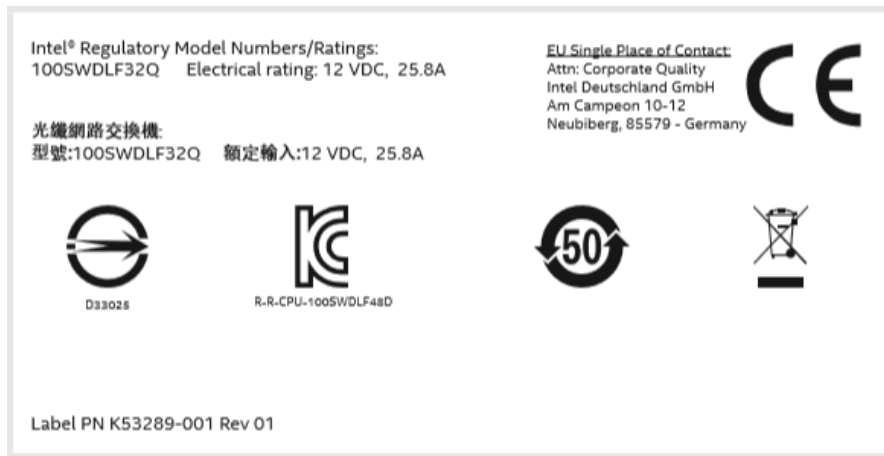
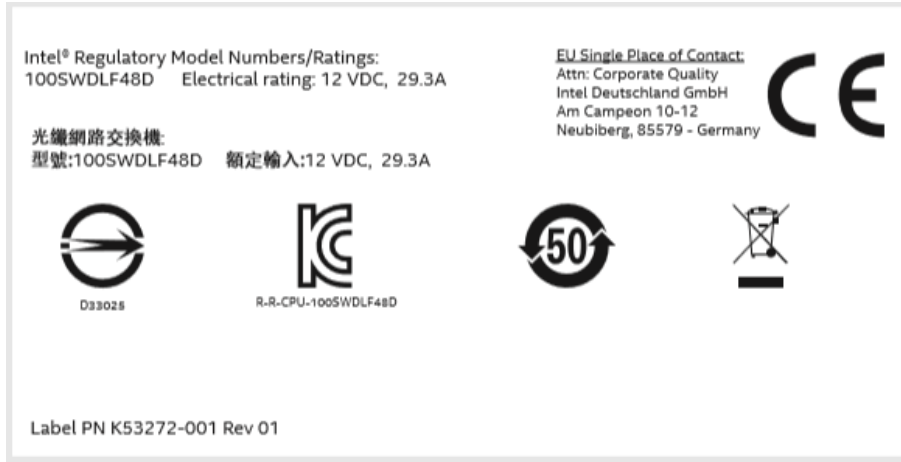


Figure 2. 100SWDLF48D Regulatory Label



Change 2: The switch firmware version on management modules shall be updated from 10.5.0.0.143/10.5.1.0.2 to 10.8.0.0.186, as shown in **Table 1** below. See switch firmware release notes for additional details. Release notes may be found with Omni-Path software postings on the Intel® download center (<https://downloadcenter.intel.com>).

Table 1. Firmware Update

DESCRIPTION	VERSION FROM	VERSION TO
Internally-Managed FW	10.5.1.0.2	10.8.0.0.186
Externally-Managed FW	10.5.0.0.143	10.8.0.0.186

Change 3: The FPGA images on management and leaf modules shall be updated according to **Table 2** below. This will eliminate the rare occurrence where a secondary reboot may be required during initialization of a module.

Table 2. FPGA Update

DESCRIPTION	VERSION FROM	VERSION TO
Management Module FPGA	A2.01	A2.02
32P Leaf FPGA – Base Board	D2.05	D3.02
32P Leaf FPGA – Mezz Board	C1.01	C2.02
48P Leaf FPGA – Base Board	70.01	No Change
48P Leaf FPGA – Mezz Board	80.01	80.02

Customer Impact of Change and Recommended Action:

Additional qualification of these changes is not required.

There is no change to the Intel Material Master (MM) numbers.

Please contact your local Intel Field Sales Representative if you have any questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change MM# Rev	Post Change MM# Rev	Pre Change TA	Post Change TA	Pre Change AA	Post Change AA
100SWD06B1N	945676	15	16	J12783-014	J12783-015	J11517-014	J11517-015
100SWD24B1N	945677	15	16	J12778-014	J12778-015	H89346-016	H89346-017
100SWDMGTSH	945776	08	09	H87892-010	H87892-011	H60416-013	H60416-014
100SWDLF32Q	945777	06	07	H94063-008	H94063-010	H94062-007	H94062-009
100SWDLF48D	961904	03	04	J63804-003	J63804-004	J63807-003	J63807-004

PCN Revision History:

Date of Revision:

October 31, 2019

Revision Number:

00

Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apagccb@intel.com

Europe Email: eccb@intel.com

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